

ABSTRACT

Provided are a method for affixing a protective film, a method for manufacturing a semiconductor component, and a protective film for use in the affixing method, which are capable of suppressing occurrence of a failure caused by a step on a main surface of a semiconductor wafer. The affixing method includes: an arrangement step of arranging a protective film 20 so as to cover a main surface A of a semiconductor wafer 10; and an affixing step of pressing the protective film 20 against the main surface 10A to affix the protective film 20 to the main surface 10A. The main surface 10A has a first region 12 in which a pump 11 is arranged, and a second region 13 which includes at least a part of a peripheral edge of the main surface 10A and in which has no pumps 11. The affixing step includes a compression step of compressing the protective film 20 in a thickness direction thereof. The compression step is performed using a pressing member 32 for pressing the protective film 20 against the main surface 10A, and a support member 33 installed along an outer peripheral edge of the second region 13.

[FIG. 6]